

Patent
09/697,619

Version with markings to show changes made

In the specification:

Paragraph beginning at page 1, line 16 has been amended as follows:

--In the manufacture of electronic equipment and appliances it is common to connect component devices such as photodiodes and lasers, for example, to circuit boards commonly termed "plug in" boards. An example of such a plug in board is a [Trans-Impedance --Amplifier] transimpedance amplifier (TIA) used in CATV-RF Broadband applications. Plug in boards permit ease of assembly or replacement and a means by which component devices in an electronic product are integrated into the circuitry of the product.--.

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In the Claims:

Claims 1, 7-8 and 10 have been amended as follows:

1. (Amended) A bracket for mounting an electrical component device comprising:
a first end, said first end having a substantially semi-circular shape and an inner and outer surface,
whereby said inner surface and said substantially semi-circular shape permit an electrical
component device to be [removably] retained thereon;

a second end; and

a shaft connecting said first and second ends, said shaft having at least one mounting point
[disposed along its length] for attaching said bracket [and said electrical component device] to a
[common] mounting surface,

wherein upon attaching said bracket to said mounting surface, said electrical component
device, retained at said first end, may be electrically connected to said mounting surface.

7. (Amended) The bracket of claim 1 wherein said a common mounting surface comprises
a [Trans-Impedance-Amplifier] transimpedance amplifier.

8. (Amended) A method for mounting an electrical component device comprising the
steps of:

mounting an electrical component device on a mounting bracket, said bracket having a first
end, the first end having a substantially semi-circular shape and an inner and outer surface,
whereby the inner surface and substantially semi-circular shape permit the electrical component
device to be retained thereon, a second end and a shaft connecting the first and second ends;

attaching said mounting bracket at the mounting point to a mounting surface ; and

connecting said electrical component device to said mounting surface.

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10. (Amended) The method of claim 8 wherein said mounting surface is a [Trans-Impedance- Amplifier] transimpedance amplifier.